

U.S. Patent Application Serial No. 10/607,514  
Amendment Under 37 C.F.R. 1.116 dated July 21, 2006  
Response to Official Action dated February 23, 2006

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Amendments to the Claims:

The following listing of claims replaces all prior versions and listings of the claims in this application.

Listing of the Claims:

1. - 28. (Cancelled).

29. (Currently Amended) A radiation cured encapsulating material having a tear resistance of less than about 2.20 pounds force, and an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi.

30. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5% ~~and a modulus at 25°C of at least about 1000 psi.~~

31. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 1.10 pounds force, ~~a modulus at 25°C in the range of from about 1000 to about 50,000 psi;~~ a percent elongation at break of at least about 10%, and an adhesion force to an underlying surface material of greater than about 0.011 pounds force.

32. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 0.44 pounds force, ~~a modulus at 25°C in the range of from about 3000 to about 25,000 psi;~~ a percent elongation at break of at least

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about 20%, and an adhesion force to an underlying surface material of greater than about 0.015 pounds force.

33. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, formed by radiation curing a composition comprising from about 30 to about 80 weight percent of a polyether-based urethane acrylate oligomer, from about 1 to about 40 weight percent of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and an effective amount of a photoinitiator for radiation curing the composition upon exposure to curing radiation.

34. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer.

35. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

36. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 40 to about 75 weight percent of the polyether-based urethane acrylate oligomer, from about 10 to about 30 weight percent of the isocyanurate monomer, and from about 0.1 to about 20 weight percent of the photoinitiator.

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37. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 50 to about 70 weight percent of the polyether-based urethane acrylate oligomer, from about 15 to about 25 weight percent of the isocyanurate monomer, and from about 1 to about 10 weight percent of the photoinitiator.
38. (Previously Presented) A radiation cured encapsulating material as defined by claim 37, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer and the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.
39. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force.
40. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force.
41. - 43. (Cancelled).
44. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.
45. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 10%.

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46. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 20%.

47. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force, ~~a modulus at 25°C of at least about 3000 psi~~, and a percent elongation at break of at least about 10%.

48. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force, ~~a modulus at 25°C in the range of from about 3000 to about 15,000 psi~~, and a percent elongation at break of at least about 20%.

49. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a viscosity-reducing component in an amount sufficient to lower the viscosity of the composition.

50. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a coefficient of friction reducing component in an amount sufficient to lower the coefficient of friction of the radiation cured material.

51. - 52. (Cancelled).